Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		V_{RM}	125	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V_{RRM} V_{RWM} V_R	100	V
RMS Reverse Voltage		$V_{R(RMS)}$	71	V
Forward Continuous Current		I_{FM}	215	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs @ t = 1.0ms @ t = 1.0s	I_{FSM}	4 1 0.5	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	500	°C/W
Operating and Storage Temperature Range	T_J , T_{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	100	—	V	I_R = 100µA
Forward Voltage	V_F	— — — —	0.715 0.855 1.0 1.25	V	I_F = 1.0mA I_F = 10mA I_F = 50mA I_F = 150mA
Peak Reverse Current (Note 6)	I_R	—	500 50 30 30	nA µA µA nA	V_R = 80V V_R = 80V, T_J = +150°C V_R = 25V, T_J = +150°C V_R = 25V
Total Capacitance	C_T	—	1.5	pF	V_R = 0V, f = 1.0MHz
Reverse Recovery Time	t_{rr}	—	4.0	ns	I_F = I_R = 10mA, I_{rr} = 0.1 x I_R, R_L = 100Ω

Notes: 5. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com.
6. Short duration pulse test used to minimize self-heating effect.

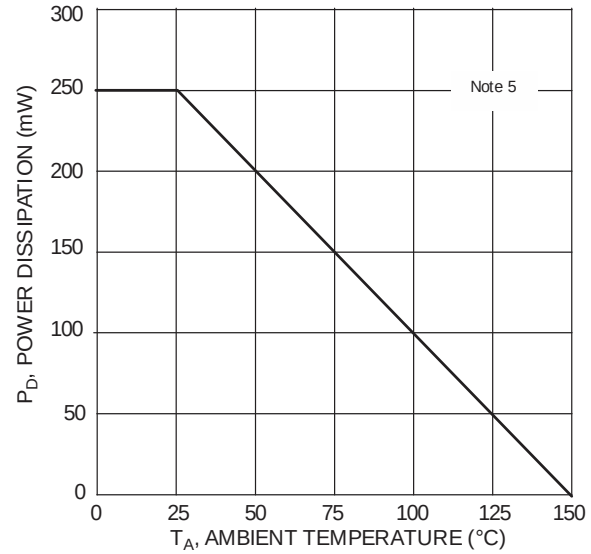


Fig. 1 Power Derating Curve

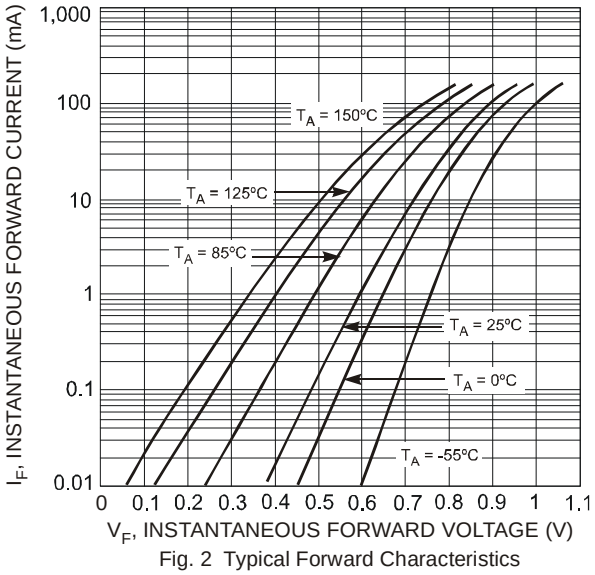


Fig. 2 Typical Forward Characteristics

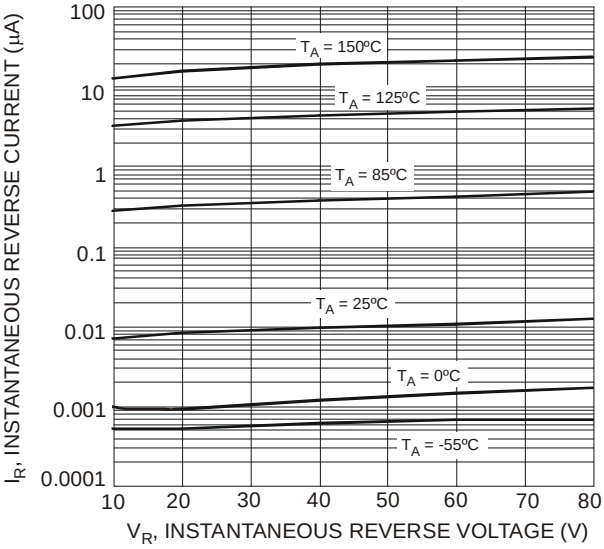


Fig. 3 Typical Reverse Characteristics

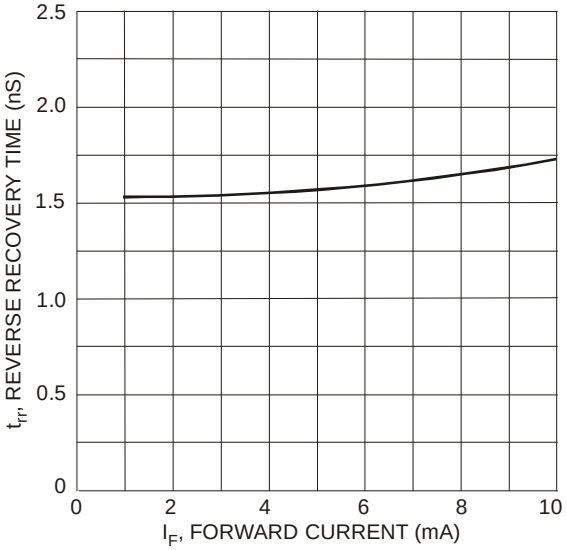


Fig. 4 Reverse Recovery Time vs. Forward Current

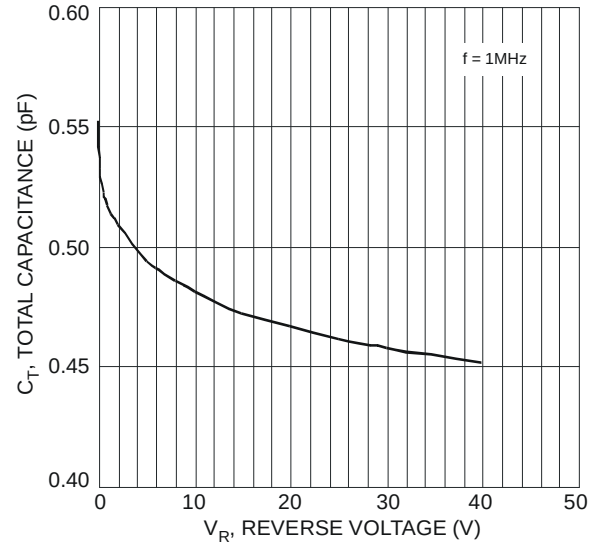
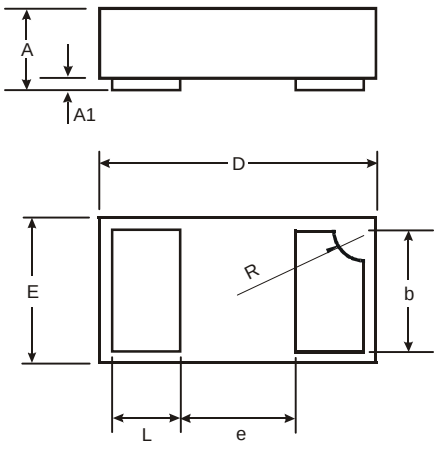


Fig. 5 Typical Total Capacitance

Package Outline Dimensions

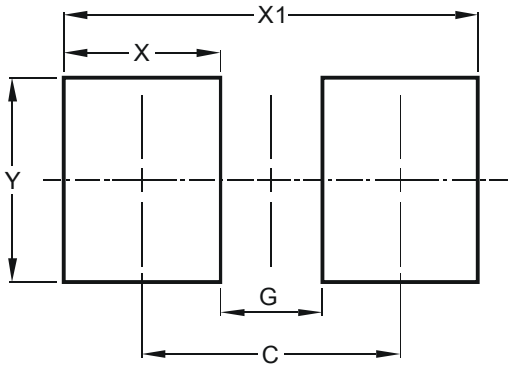
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-2			
Dim	**Min**	**Max**	**Typ**
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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